PCN Number: 201910140		PCN Date:		Oct.	Oct. 16, 2019		
Title: Datasheet for							
Customer Contact:	PCN Manager			De	pt:	Quality Services	
Change Type:					•	, ,	
Assembly Site		Design			Wafe	er Bump Site	
Assembly Process		✓ Data Sheet			Wafer Bump Material		
Assembly Materials		Part number change				er Bump Process	
Mechanical Specification		Test Site				er Fab Site	
Packing/Shipping/Labeling		Test Process				er Fab Materials	
	Not	tification	n Details		ware	er Fab Process	
Description of Chang		LITICALIO	Details				
Texas Instruments Inco		uncing an	information o	nly no	tificat	tion	
The product datasheet					, cirroa		
The following change h				••			
ine reneming analige in	istory provides re						
TEXAS							
INSTRUMENTS			_			TMP10	
			S	BOS663A	-APRIL 2	2013-REVISED SEPTEMBER 20	
Changes from Original (Ap	ril 2013) to Revision A	4				Page	
Added Pin Configuration	and Functions section,	ESD Ratings	table, Feature De	scription	section	n, Device Functional	
Modes, Application and I	mplementation section,	Power Suppl	y Recommendatio	ns section	on, <i>Lay</i> o	out section, Device	
		_	-			ection1	
						3	
						3	
						+ 0.5) and ≤ 4 V	
• Changed remperature E	rror at +25°C grapn					8	
The datasheet number	will be changing.						
Device Family		Change	From:		Chan	ge To:	
TMP108		SBOS663	3		SBOS	5663A	
These changes may be	reviewed at the o	datasneet	links provided	1.			
http://www.ti.com/pro	duct/TMP108						
Reason for Change:							
To accurately reflect de	evice characteristi	cs.					
Anticipated impact o	n Fit, Form, Fur	nction, Qu	ality or Reli	ability	y (po	sitive / negative):	
No anticipated impact. to the actual device.	This is a specifica	ation chang	ge announcen	nent o	nly. T	here are no changes	
Changes to product i	dentification re	sulting fr	om this PCN	:			
None.							
Product Affected:							
TMP108AIYFFR	TMD400450		<u> </u>				
THE TOOMTHEE	TMD108ATVFF	ı	1			Î.	

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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